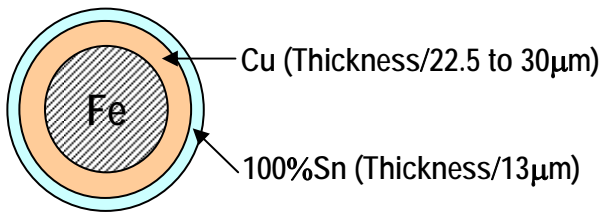


FPCAP Functional Polymer Aluminum Solid Electrolytic Capacitors

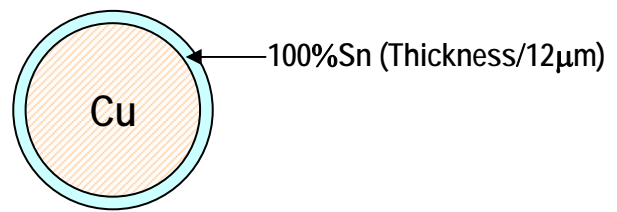
Materials

Terminals

Fe wire

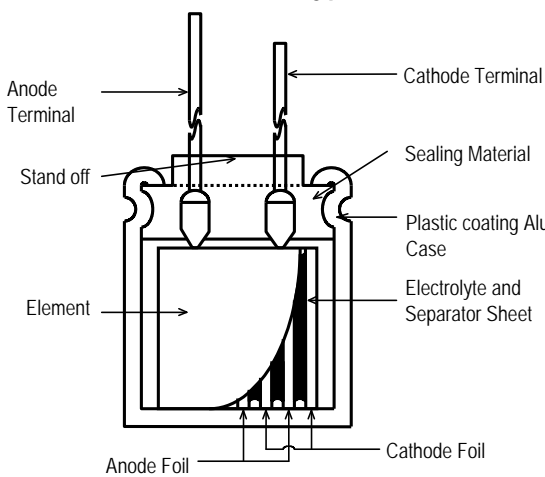


Cu wire

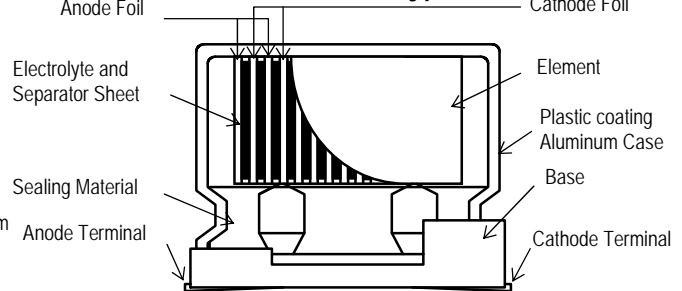


Compositions

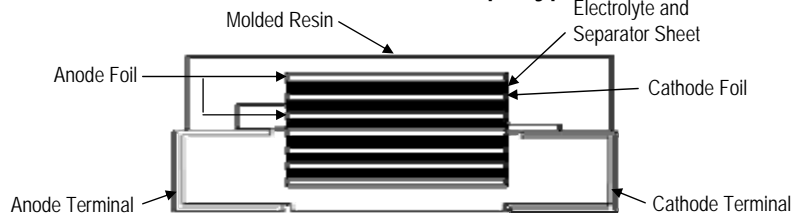
Radial Lead Type



SMD (Can) Type



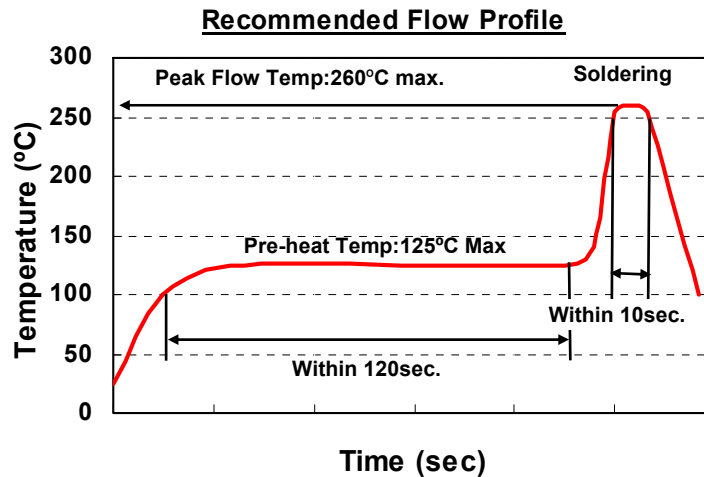
SMD (Molded Chip) Type



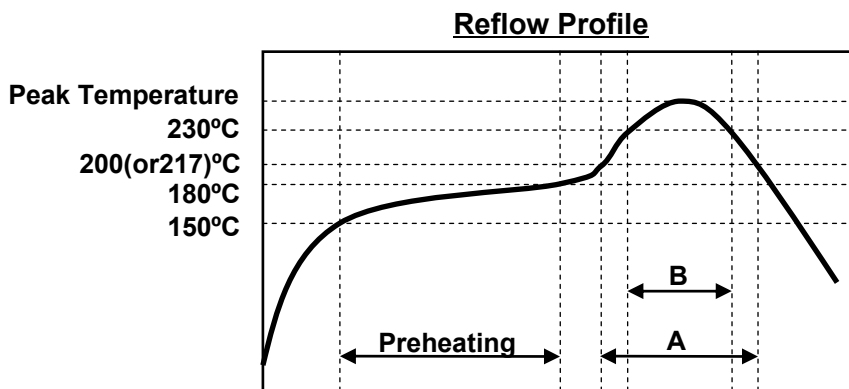
Composition Part	Materials		
	Radial Lead Type	SMD Type	
		Can Type	Molded Chip Type
Anode Foil	Aluminum		
Cathode Foil	Aluminum		
Separator Sheet	Electrolytic Capacitor Paper		
Electrolyte	Functional Polymer		
Terminal	1)Iron Lead / Copper Plating + Tin Plating 2)Copper Lead / Tin Plating	Copper Lead / Tin Plating	Copper Lead / Palladium + Gold Plating
Aluminum Case	Aluminum + Plastic		-
Sealing Material	Rubber		-
Base	-	Plastic	-
Molded Resin	-	-	Epoxy Resin

Soldering Profile

Flow Soldering (Radial Lead Type)



Reflow Soldering (SMD Type)



Item	<i>PS, PA, HS, HA, SS, SA, SB, FS, FA, SL</i>		<i>VA, VB, VC, UA, UB</i>	
	Recommended Condition 1	Recommended Condition 2	Recommended Condition 3	Recommended Condition 4
Peak Temperature	260°C or less	250°C or less	260°C or less (Within 5 seconds)	250°C or less (Within 5 seconds)
Preheating	150°C to 180°C Within 90 seconds	150°C to 180°C Within 90 seconds	150°C to 180°C Within 90 seconds	150°C to 180°C Within 120 seconds
A	200°C and higher Within 60 seconds	200°C and higher Within 60 seconds	217°C and higher Within 60 seconds	217°C and higher Within 60 seconds
B	230°C and higher Within 40 seconds	230°C and higher Within 40 seconds	-	-
The Number of Reflow	Only 1 time	Twice or less	Only 1 time	Twice or less